

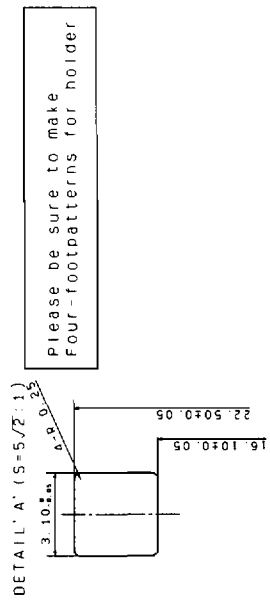
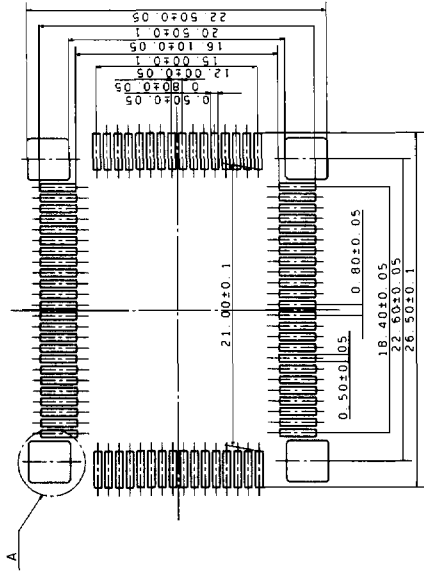
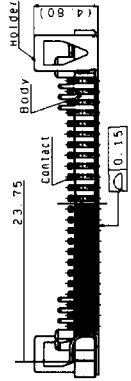
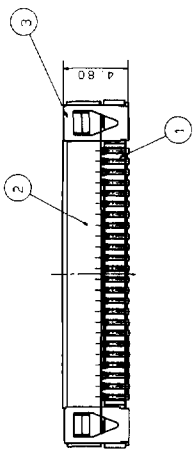
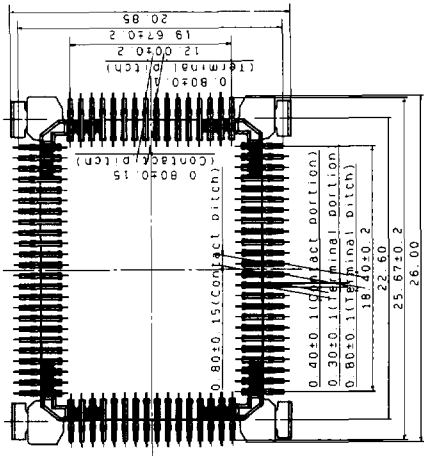
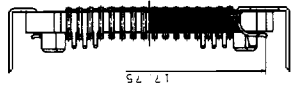
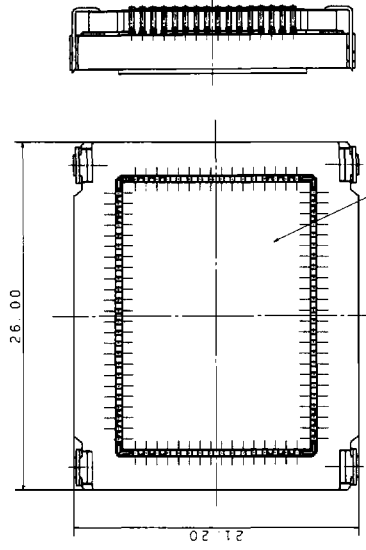
Specifications for QFP Sockets

MATERIALS	
Body: Glass-filled PPS Frame: Glass-filled PPS Contacts: Copper alloy Holder: Copper alloy Flammability: UL 94V-0	Plating: TT = 2.03 μm (80 μinch) Tin/Lead overall. 1.27 μm (50 μinch) Nickel Underplate.
MECHANICAL	
Shock Resistance: 980m/s ² (100G)	
ELECTRICAL	
Current Rating: 0.2 Ampere per contact Insulation Resistance: Minimum 1000m Ω Contact Resistance: Maximum 50m Ω	
ENVIRONMENTAL	APPLICABLE IC
Operating Temperature: -55°C to + 85°C Thermal Shock Resistance: Contact Resistance: Max. 50m Ω Insulation Resistance: Min. 100M Ω Humidity Resistance: Contact Resistance: Max. 50m Ω Insulation Resistance: Min. 100M Ω H₂S Gas Resistance: Contact Resistance: Max. 50m Ω SO₂ Gas Resistance: Contact Resistance: Max. 50m Ω Soldering Heat Resistance: Peak temperature of 245°C 300°C within 5 seconds	64 contacts: Motorola NEC: P64GC-80-AB8-1 80 contacts: NEC: P80G-80-12-2 P80G-80-1C-2 Hitachi: FP-80 FP-80-B Mitsubishi: 80P6-B 80P6N-C Fujitsu: FPT-80P-M06 FPT-80P-M07 FPT-80P-M08 Toshiba: QFP80-P-1420 QFP80-P-1420A QFP80-P-1420B QFP80-P-1420C Sanyo: 3044B

SOCKETS

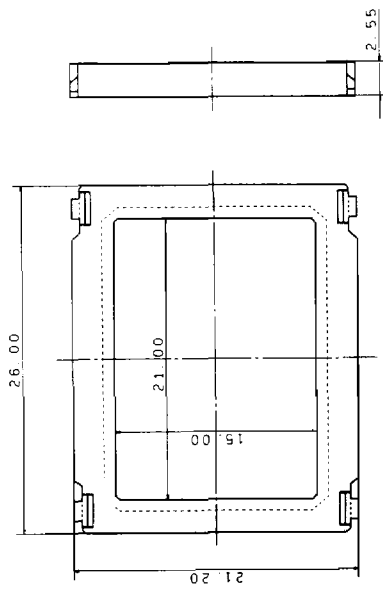
SOCKETS

QFP-80 8 — SMT N — TT
 Number of Contacts: 80
 8 = 8mm Contact Spacing
 N = NEC Type
 Plating



± 0.3 General Tolerance

Recommended PC board pattern (TOP VIEW)



ALL DIMENSIONS IN MILLIMETERS

- 1 = Body
- 2 = Frame
- 3 = IC Socket

Robinson Nugent
 812/945-0211
 812/945-0805 FAX

QFP-808-SMTN-TT
 80 Position, SMT QFP Socket (.8mm contact spacing),
 NEC Type, Socket and Frame